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(54) **BOARD EDGE ELECTRICAL CONTACT STRUCTURES**

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(57) **ABSTRACT**

A printed circuit board for mounting electrical components thereupon include: a first side; a second side opposite the first side; electrical connection points disposed on the surface of an exterior edge of the printed circuit board; and wherein the exterior edge of the printed circuit board is between the first side and the second side. Further a method of manufacturing a printed circuit board for mounting electrical components thereupon includes the steps of disposing interconnect structures within the printed circuit board adjacent to at least one edge of the printed circuit board; and removing material from the printed circuit board edge to expose the interconnect structures such that the exposed interconnect structures correspond to a component connection footprint.

